

PATENT APPLICATION
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q67930

Hiroki TAKEUCHI, et al.

Appln. No.: 10/026,454

Group Art Unit: 2826

Confirmation No.: 1274

Examiner: Alexander O. Williams

Filed: December 27, 2001

For: EMBEDDING RESIN AND WIRING SUBSTRATE USING THE SAME

SUBMISSION OF TERMINAL DISCLAIMER

Commissioner for Patents
Washington, D.C. 20231

Sir:

Submitted herewith is a Terminal Disclaimer in the above-identified application. A check in the amount of \$110.00 is attached. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this Submission is attached.

Respectfully submitted,



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WASHINGTON OFFICE



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PATENT TRADEMARK OFFICE

Date: April 17, 2003

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APPROVED

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TERMINAL DISCLAIMER
Sharon S. Hoppe
SHARON S. HOPPE
PARALEGAL SPECIALIST
TECHNOLOGY CENTER 2800

JUN 20 2003

TECHNOLOGY CENTER 2800
SPECIAL PROGRAM CENTER

Sir:

The undersigned, on behalf of the petitioner, NGK SPARK PLUG CO., LTD., represents that the petitioner, NGK SPARK PLUG CO., LTD. is the owner of (1) the entire right, title and interest of U.S. Application No. 10/024,601, filed on December 21, 2001 for EMBEDDING RESIN by virtue of an Assignment from all of the inventors thereof executed on January 23 and 29, 2002, recorded on March 7, 2002 at Reel 012661, Frame 0137; (2) the entire right, title and interest of U.S. Application No. 10/025,764, filed on December 26, 2001 for EMBEDDING RESIN AND WIRING SUBSTRATE USING THE SAME by virtue of an Assignment from all of the inventors thereof executed on January 21, 2002, recorded on June 11, 2002 at Reel 012976, Frame 0187; (3) the entire right, title and interest of U.S. Application No. 10/042,317, filed on January 11, 2002 for EMBEDDING RESIN, WIRING SUBSTRATE USING SAME AND PROCESS FOR PRODUCING WIRING SUBSTRATE USING SAME by virtue of an Assignment from all of the inventors thereof executed on February 5, 2002, recorded on March

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U.S. Patent Application Ser. No.: 10/026,454

18, 2002 at Reel 012694, Frame 0450; (4) the entire right, title and interest of U.S. Application No. 10/024,581, filed on December 21, 2001 for WIRING BOARD by virtue of an Assignment from all of the inventors thereof executed on January 23, 2002 and January 29, 2002, recorded on March 11, 2002 at Reel 012694, Frame 0785; (5) the entire right, title and interest of U.S. Application No. 10/026,928, filed on December 27, 2001 for WIRING BOARD AND METHOD FOR FABRICATING THE SAME by virtue of an Assignment from all of the inventors thereof executed on January 23, 2002 and January 29, 2002, recorded on March 11, 2002 at Reel 012689, Frame 0648; and (6) the entire right, title and interest in the above-captioned U.S. Application No. 10/026,454 by virtue of an Assignment from all of the inventors thereof executed on January 18, 2002, recorded on March 8, 2002, at Reel 012667, Frame 0841.

Petitioner hereby certifies that the above-mentioned Assignments have been reviewed and to the best of petitioner's knowledge and belief, title is in petitioner who is seeking to take this action.

Petitioner hereby disclaims the terminal part of any patent granted on the above-captioned U.S. Application No. 10/026,454 which would extend beyond the expiration of the full statutory term as presently shortened by any terminal disclaimer of any patent issuing from U.S. Application Nos. 10/024,601, 10/025,764, 10/042,317, 10/024,581 and 10/026,928, and hereby agrees that any patent so granted on the above-captioned U.S. Application No. 10/026,454 shall be enforceable only for and during such period that the legal title to any patent issuing from U.S. Application Nos. 10/024,601, 10/025,764, 10/042,317, 10/024,581 and 10/026,928 shall be the same as the legal title to said patent issuing from the above-captioned U.S. Application No. 6,586,827

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10/026,454, this agreement to run with any patent granted on the above-captioned U.S.

Application No. 10/026,454 and to be binding upon the grantee, its successors or assigns.

Petitioner does not disclaim any terminal part of any patent granted on the above-captioned U.S. Application No. 10/026,454 prior to the expiration date of the full statutory term as presently shortened by any terminal disclaimer of any patent issuing from U.S. Application Nos. 10/024,601, 10/025,764, 10/042,317, 10/024,581 and 10/026,928 in the event that any patent issuing from U.S. Application Nos. 10/024,601, 10/025,764, 10/042,317, 10/024,581 and 10/026,928 later expires for failure to pay a maintenance fee, is held unenforceable, is found invalid, is statutorily disclaimed in whole or terminally disclaimed under 37 C.F.R. § 1.321(a), has all claims cancelled by a Reexamination Certificate, or is otherwise terminated prior to the expiration of its statutory term as presently shortened by any terminal disclaimer, except for the separation of legal title stated above.

The undersigned whose signature and title appear below is empowered to act on behalf of petitioner.

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I declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements are made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001, Title 18, of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Respectfully submitted,

Date: April 2, 2003

Kazuhiko Obayashi

Title: Deputy General Manager